



February 2012

### FSUSB42 — Low-Power, Two-Port, Hi-Speed, USB2.0 (480Mbps) UART Switch

#### **Features**

- Low On Capacitance: 3.7pF Typical
   Low On Resistance: 3.9Ω Typical
- Low Power Consumption: 1µA Maximum
  - 15 $\mu$ A Maximum I<sub>CCT</sub> over an Expanded Voltage Range (V<sub>IN</sub>=1.8V, V<sub>CC</sub>=4.4V)
- Wide -3db Bandwidth: > 720MHz
- Packaged in:
  - 10-Lead UMLP (1.4 x 1.8mm)
  - 10-Lead MSOP
- 8kV ESD Rating, >16kV Power/GND ESD Rating
- Over-Voltage Tolerance (OVT) on all USB Ports Up to 5.25V without External Components

#### **Applications**

- Cell phone, PDA, Digital Camera, and Notebook
- LCD Monitor, TV, and Set-Top Box

#### **IMPORTANT NOTE:**

For additional performance information, please contact analogswitch@fairchildsemi.com.

#### Description

The FSUSB42 is a bi-directional, low-power, two-port, Hi-Speed, USB2.0 switch. Configured as a double-pole, double-throw switch (DPDT) switch, it is optimized for switching between two Hi-Speed (480Mbps) sources or a Hi-Speed and Full-Speed (12Mbps) source.

The FSUSB42 is compatible with the requirements of USB2.0 and features an extremely low on capacitance ( $C_{ON}$ ) of 3.7pF. The wide bandwidth of this device (720MHz) exceeds the bandwidth needed to pass the third harmonic, resulting in signals with minimum edge and phase distortion. Superior channel-to-channel crosstalk also minimizes interference.

The FSUSB42 contains special circuitry on the switch I/O pins for applications where the  $V_{\text{CC}}$  supply is powered-off ( $V_{\text{CC}}{=}0$ ), which allows the device to withstand an over-voltage condition. This device is designed to minimize current consumption even when the control voltage applied to the SEL pin is lower than the supply voltage ( $V_{\text{CC}}$ ). This feature is especially valuable to ultra-portable applications, such as cell phones, allowing for direct interface with the general-purpose I/Os of the baseband processor. Other applications include switching and connector sharing in portable cell phones, PDAs, digital cameras, printers, and notebook computers.

#### **Ordering Information**

Part Number	Top Mark	Operating Temperature Range	Package
FSUSB42UMX	HE	-40 to +85°C	10-Lead, Quad, Ultrathin Molded Leadless Package (UMLP), 1.4 x 1.8mm
FSUSB42MUX	FSUSB42 -40 to +85°C		10-Lead, Molded Small Outline Package (MSOP) JEDEC MO-187, 3.0mm Wide

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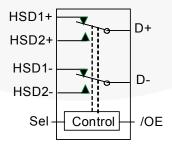


Figure 1. Analog Symbol

#### **Pin Assignments**

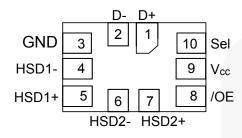


Figure 2. Pin Assignment 10L UMLP (Top Through View)

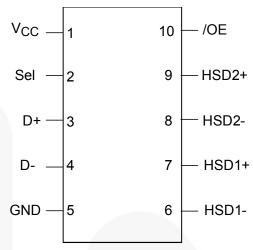


Figure 3. Pin Assignment 10L MSOP (Top Through View)

#### **Pin Definitions**

UMLP Pin#	MSOP Pin#	Name	Description	
1	3	D+	USB Data Bus	
2	4	D-	USB Data Bus	
3	5	GND	Ground	
4	6	HSD1-	Multiplexed Source Inputs (UART / USB)	
5	7	HSD1+	Multiplexed Source Inputs (UART / USB)	
6	8	HSD2-	Multiplexed Source Inputs (USB Only)	
7	9	HSD2+	Multiplexed Source Inputs (USB Only)	
8	10	/OE	Switch Enable	
9	1	V <sub>CC</sub>	Supply Voltage	
10	2	Sel	Switch Select	

#### **Truth Table**

Sel	/OE	Function
X	HIGH	Disconnect
LOW	LOW	D+, D-=HSD1+, HSD1-
HIGH	LOW	D+, D-=HSD2+, HSD2-

#### **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Min.	Max.	Unit	
V <sub>CC</sub>	Supply Voltage		-0.5	5.6	V
V <sub>CNTRL</sub>	DC Input Voltage (S, /OE) <sup>(1)</sup>		-0.5	V <sub>CC</sub>	V
V <sub>SW</sub>	DC Switch I/O Voltage <sup>(1)</sup>		-0.50	5.25	V
I <sub>IK</sub>	DC Input Diode Current		-50		mA
l <sub>OUT</sub>	DC Output Current			100	mA
T <sub>STG</sub>	Storage Temperature		-65	+150	°C
MSL	Moisture Sensitivity Level (JEDEC J-STD-020	JA)		1	Level
		All Pins	7		
	III B. I M. I I IEDEO IEDDO A444	I/O to GND	8		
	Human Body Model, JEDEC: JESD22-A114	Power to GND	16		
ESD		D+/D-	9		kV
	IEC 61000-4-2 System on USB Connector	Air Discharge	15		
	Pins D+ & D-	Contact	8		
	Charged Device Model, JEDEC: JESD22-C10	)1	2		

#### Note:

1. The input and output negative ratings may be exceeded if the input and output diode current ratings are observed.

#### **Recommended Operating Conditions**

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Min.	Max.	Unit
Vcc	Supply Voltage	3.0	4.4	V
V <sub>CNTRL</sub> <sup>(2)</sup>	Control Input Voltage (S, /OE)	0	Vcc	V
V <sub>SW</sub>	Switch I/O Voltage	-0.5	4.5	V
T <sub>A</sub>	Operating Temperature	-40	+85	°C

#### Note:

2. The control input must be held HIGH or LOW and it must not float.

#### **DC Electrical Characteristics**

All typical value are at  $T_A$ =25°C unless otherwise specified.

Coursels at	Donometer	Condition	V 00	T <sub>A</sub> =- 40°C to +85°C			11!4
Symbol	Parameter	Condition	V <sub>cc</sub> (V)	Min.	Тур.	Max.	Unit
V <sub>IK</sub>	Clamp Diode Voltage	I <sub>IN</sub> =-18mA	3.0			-1.2	V
V	Innut Voltago High		3.0 to 3.6	1.3			V
V <sub>IH</sub>	Input Voltage High		4.3	1.7			V
W	Innut Voltago Low		3.0 to 3.6			0.5	V
V <sub>IL</sub>	Input Voltage Low		4.3			0.7	V
I <sub>IN</sub>	Control Input Leakage	V <sub>SW</sub> =0 to V <sub>CC</sub>	0 to 4.3	-1		1	μΑ
l <sub>oz</sub>	Off State Leakage	0 ≤ Dn, HSD1n, HSD2n ≤ 3.6V	4.3	-2		2	μΑ
l <sub>OFF</sub>	Power-Off Leakage Current (All I/O Ports)	V <sub>SW</sub> =0V to 4.3V, V <sub>CC</sub> =0V Figure 5	0	-2		2	μΑ
Ron	HS Switch On Resistance <sup>(3)</sup>	V <sub>SW</sub> =0.4V, I <sub>ON</sub> =-8mA Figure 4,	3.0		3.9	6.5	Ω
ΔRon	HS Delta R <sub>ON</sub> <sup>(4)</sup>	V <sub>SW</sub> =0.4V, I <sub>ON</sub> =-8mA	3.0		0.65		Ω
I <sub>CC</sub>	Quiescent Supply Current	V <sub>CNTRL</sub> =0 or V <sub>CC</sub> , I <sub>OUT</sub> =0	4.3			1	μΑ
	Increase in I <sub>CC</sub> Current per	V <sub>CNTRL</sub> =2.6V, V <sub>CC</sub> =4.3V	4.3			10	μΑ
Ісст	Control Voltage and V <sub>CC</sub>	V <sub>CNTRL</sub> =1.8V, V <sub>CC</sub> =4.3V	4.3			15	μΑ

#### Notes:

- 3. Measured by the voltage drop between HSDn and Dn pins at the indicated current through the switch. On resistance is determined by the lower of the voltage on the two (HSDn or Dn ports).
- 4. Guaranteed by characterization.

#### **AC Electrical Characteristics**

All typical value are for  $V_{\text{CC}}$ =3.3V at  $T_{\text{A}}$ =25°C unless otherwise specified.

Cumbal	Baramatar	Condition	V 00	T <sub>A</sub> =- 40°C to +85°C			Unit	
Symbol	Parameter	Condition	V <sub>CC</sub> (V)	Min.	Тур.	Max.	Oill	
t <sub>ON</sub>	Turn-On Time S, /OE to Output	$R_L$ =50 $\Omega$ , $C_L$ =5pF $V_{SW}$ =0.8V Figure 6, Figure 7	3.0 to 3.6		13	30	ns	
t <sub>OFF</sub>	Turn-Off Time S, /OE to Output	$R_L$ =50 $\Omega$ , $C_L$ =5pF $V_{SW}$ =0.8V Figure 6, Figure 7	3.0 to 3.6		12	25	ns	
t <sub>PD</sub>	Propagation Delay <sup>(5)</sup>	$C_L$ =5 pF, $R_L$ =50 $\Omega$ Figure 6, Figure 8	3.3		0.25		ns	
t <sub>ввм</sub>	Break-Before-Make	$R_L$ =50 $\Omega$ , $C_L$ =5pF $V_{SW1}$ = $V_{SW2}$ =0.8V Figure 10	3.0 to 3.6	2.0		6.5	ns	
O <sub>IRR</sub>	Off Isolation	$R_L$ =50 $\Omega$ , f=240MHz Figure 12	3.0 to 3.6		-30		dB	
Xtalk	Non-Adjacent Channel Crosstalk	$R_L$ =50 $\Omega$ , f=240MHz Figure 13	3.0 to 3.6		-45		dB	
BW	-3db Bandwidth	$R_L$ =50 $\Omega$ , $C_L$ =0pF Figure 11	3.0 to 3.6		720		MHz	
DVV	-Sub Balluwidti	$R_L$ =50 $\Omega$ , $C_L$ =5pF Figure 11	3.0 10 3.0		550		MHz	

#### Note:

#### **USB Hi-Speed-Related AC Electrical Characteristics**

Symbol	Doromotor	Condition	V 00	T <sub>A</sub> =- 40°C to +85°C			Unit
Symbol	Parameter	Condition	V <sub>cc</sub> (V)	Min.	Тур.	Max.	Unit
$t_{SK(P)}$	Skew of Opposite Transitions of the Same Output <sup>(6)</sup>	$C_L$ =5pF, $R_L$ =50 $\Omega$ Figure 9	3.0 to 3.6	1	20		ps
t <sub>J</sub>	Total Jitter <sup>(6)</sup>	$R_L$ =50 $\Omega$ , $C_L$ =5pf, $t_R$ = $t_F$ =500ps (10-90%) at 480Mbps (PRBS= $2^{15}$ – 1)	3.0 to 3.6		200		ps

#### Note:

#### Capacitance

Cumbal	Doromotor	Condition	T <sub>A</sub> =- 40°C to +85°C			Unit
Symbol	Parameter	Condition	Min.	Тур.	Max.	Onit
C <sub>IN</sub>	Control Pin Input Capacitance	V <sub>CC</sub> =0V		1.5		
C <sub>ON</sub>	D+/D- On Capacitance	V <sub>CC</sub> =3.3V, /OE=0V, f=240MHz Figure 15		3.7		pF
C <sub>OFF</sub>	D1n, D2n Off Capacitance	V <sub>CC</sub> and /OE=3.3V Figure 14		2.0		

<sup>5.</sup> Guaranteed by characterization.

<sup>6.</sup> Guaranteed by characterization.

#### **Test Diagrams**

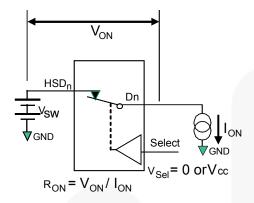
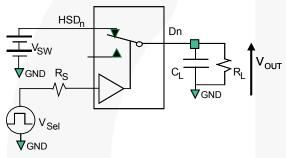
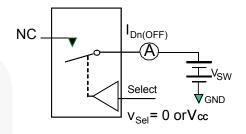


Figure 4. On Resistance



 $R_L$ ,  $R_S$ , and  $C_L$  are functions of the application environment (see AC Tables for specific values)  $C_L$  includes test fixture and stray capacitance.

Figure 6. AC Test Circuit Load



\*\*Each switch port is tested separately

Figure 5. Off Leakage

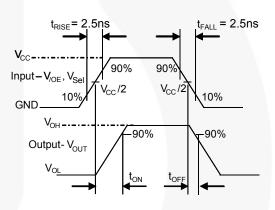


Figure 7. Turn-On / Turn-Off Waveforms

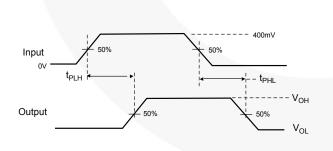


Figure 8. Propagation Delay (t<sub>R</sub>t<sub>F</sub> - 500ps)

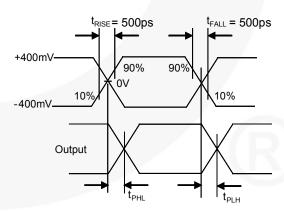


Figure 9. Intra-Pair Skew Test t<sub>SK(P)</sub>

# Test Diagrams (Continued) $V_{CC}$ $V_{CC}$

Figure 10. Break-Before-Make Interval Timing

C<sub>L</sub> includes test fixture and stray capacitance.

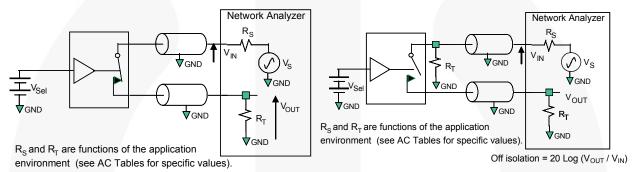


Figure 11. Bandwidth

Figure 12. Channel Off Isolation

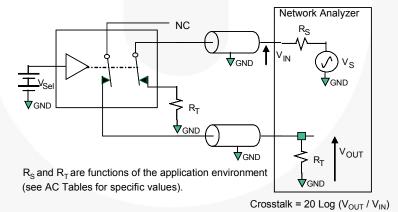


Figure 13. Non-Adjacent Channel-to-Channel Crosstalk

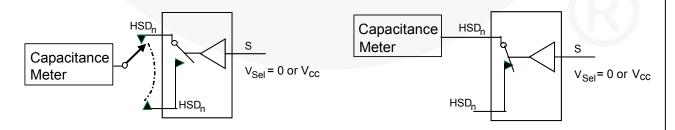


Figure 14. Channel Off Capacitance

Figure 15. Channel On Capacitance

#### **Physical Dimensions**

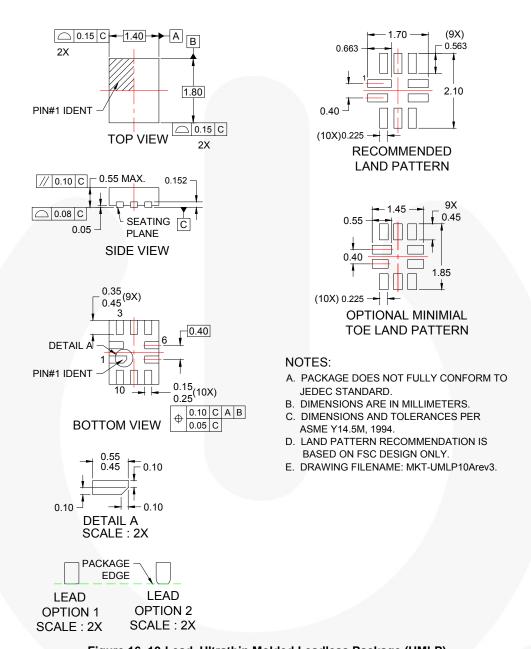


Figure 16. 10-Lead, Ultrathin Molded Leadless Package (UMLP)

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## 3.00±0.10

Α

В

4.90

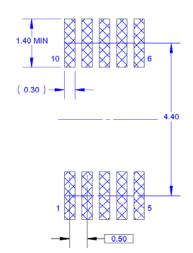
3.00±0.10

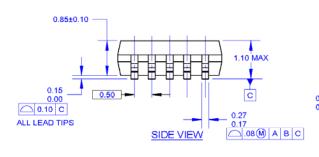
Physical Dimensions (Continued)

2.45

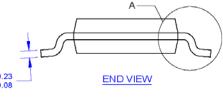
PIN#1 ID QUADRANT

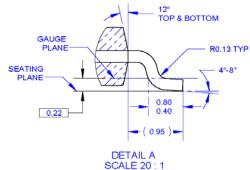
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TOP VIEW





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- Y14.5-1994. LAND PATTERN AS PER IPC7351#SOP50P490X110-10AN FILE NAME: MKT-MUA10AREV3

#### Figure 17. 10-Lead, Molded Small Outline Package (MSOP)

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